+44 20 8123 2220
info@marketpublishers.com

Global 2.5D and 3D IC Packaging Supply, Demand and Key Producers, 2023-2029

https://marketpublishers.com/r/GF887B996E90EN.html
Date: April 2023
Pages: 124
Price: US$ 4,480.00 (Single User License)
ID: GF887B996E90EN

Abstracts

The global 2.5D and 3D IC Packaging market size is expected to reach $ million by 2029, rising at a market growth of % CAGR during the forecast period (2023-2029).

In 2.5D structure, two or more active semiconductor chips are placed side-by-side on a silicon interposer for achieving extremely high die-to-die interconnect density. In 3D structure, active chips are integrated by die stacking for shortest interconnect and smallest package footprint.

This report studies the global 2.5D and 3D IC Packaging demand, key companies, and key regions.

This report is a detailed and comprehensive analysis of the world market for 2.5D and 3D IC Packaging, and provides market size (US$ million) and Year-over-Year (YoY) growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of 2.5D and 3D IC Packaging that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global 2.5D and 3D IC Packaging total market, 2018-2029, (USD Million)

Global 2.5D and 3D IC Packaging total market by region & country, CAGR, 2018-2029, (USD Million)

U.S. VS China: 2.5D and 3D IC Packaging total market, key domestic companies and share, (USD Million)

Global 2.5D and 3D IC Packaging revenue by player and market share 2018-2023, (USD Million)

Global 2.5D and 3D IC Packaging total market by Type, CAGR, 2018-2029, (USD Million)

Global 2.5D and 3D IC Packaging total market by Application, CAGR, 2018-2029, (USD Million)

This reports profiles major players in the global 2.5D and 3D IC Packaging market based on the following parameters – company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include ASE Technology, Samsung Electronics, Toshiba, STMicroelectronics, Xilinx, Intel, Micron Technology, TSMC and SK Hynix, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals, COVID-19 and Russia-Ukraine War Influence.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World 2.5D and 3D IC Packaging market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US$ Millions), by player, by regions, by Type, and by Application. Data is given for the years 2018-2029 by year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

Global 2.5D and 3D IC Packaging Market, By Region:

United States

China

Europe

Japan

+44 20 8123 2220
info@marketpublishers.com

South Korea

ASEAN

India

Rest of World

Global 2.5D and 3D IC Packaging Market, Segmentation by Type

2.5D

3D TSV

3D Wafer-level Chip-scale Packaging

Global 2.5D and 3D IC Packaging Market, Segmentation by Application

Consumer Electronics

Medical Devices

Communications and Telecom

Automotive

Other

Companies Profiled:

ASE Technology

Samsung Electronics

Toshiba

STMicroelectronics

Xilinx

Intel

Micron Technology

TSMC

SK Hynix

Amkor Technology

GlobalFoundries

SanDisk (Western Digital)

Synopsys

Invensas

Siliconware Precision Industries

Jiangsu Changjiang Electronics

Powertech Technology

Key Questions Answered

1. How big is the global 2.5D and 3D IC Packaging market?

2. What is the demand of the global 2.5D and 3D IC Packaging market?

3. What is the year over year growth of the global 2.5D and 3D IC Packaging market?

4. What is the total value of the global 2.5D and 3D IC Packaging market?

+44 20 8123 2220
info@marketpublishers.com

5. Who are the major players in the global 2.5D and 3D IC Packaging market?

6. What are the growth factors driving the market demand?

+44 20 8123 2220
info@marketpublishers.com

Contents

1 SUPPLY SUMMARY

1.1 2.5D and 3D IC Packaging Introduction
1.2 World 2.5D and 3D IC Packaging Market Size & Forecast (2018 & 2022 & 2029)
1.3 World 2.5D and 3D IC Packaging Total Market by Region (by Headquarter Location)
  1.3.1 World 2.5D and 3D IC Packaging Market Size by Region (2018-2029), (by Headquarter Location)
  1.3.2 United States 2.5D and 3D IC Packaging Market Size (2018-2029)
  1.3.3 China 2.5D and 3D IC Packaging Market Size (2018-2029)
  1.3.4 Europe 2.5D and 3D IC Packaging Market Size (2018-2029)
  1.3.5 Japan 2.5D and 3D IC Packaging Market Size (2018-2029)
  1.3.6 South Korea 2.5D and 3D IC Packaging Market Size (2018-2029)
  1.3.7 ASEAN 2.5D and 3D IC Packaging Market Size (2018-2029)
  1.3.8 India 2.5D and 3D IC Packaging Market Size (2018-2029)
1.4 Market Drivers, Restraints and Trends
  1.4.1 2.5D and 3D IC Packaging Market Drivers
  1.4.2 Factors Affecting Demand
  1.4.3 2.5D and 3D IC Packaging Major Market Trends
1.5 Influence of COVID-19 and Russia-Ukraine War
  1.5.1 Influence of COVID-19
  1.5.2 Influence of Russia-Ukraine War

2 DEMAND SUMMARY

2.1 World 2.5D and 3D IC Packaging Consumption Value (2018-2029)
2.2 World 2.5D and 3D IC Packaging Consumption Value by Region
  2.2.1 World 2.5D and 3D IC Packaging Consumption Value by Region (2018-2023)
  2.2.2 World 2.5D and 3D IC Packaging Consumption Value Forecast by Region (2024-2029)
2.3 United States 2.5D and 3D IC Packaging Consumption Value (2018-2029)
2.4 China 2.5D and 3D IC Packaging Consumption Value (2018-2029)
2.5 Europe 2.5D and 3D IC Packaging Consumption Value (2018-2029)
2.6 Japan 2.5D and 3D IC Packaging Consumption Value (2018-2029)
2.7 South Korea 2.5D and 3D IC Packaging Consumption Value (2018-2029)
2.8 ASEAN 2.5D and 3D IC Packaging Consumption Value (2018-2029)
2.9 India 2.5D and 3D IC Packaging Consumption Value (2018-2029)

+44 20 8123 2220
info@marketpublishers.com

3 WORLD 2.5D AND 3D IC PACKAGING COMPANIES COMPETITIVE ANALYSIS

3.1 World 2.5D and 3D IC Packaging Revenue by Player (2018-2023)
3.2 Industry Rank and Concentration Rate (CR)
  3.2.1 Global 2.5D and 3D IC Packaging Industry Rank of Major Players
  3.2.2 Global Concentration Ratios (CR4) for 2.5D and 3D IC Packaging in 2022
  3.2.3 Global Concentration Ratios (CR8) for 2.5D and 3D IC Packaging in 2022
3.3 2.5D and 3D IC Packaging Company Evaluation Quadrant
3.4 2.5D and 3D IC Packaging Market: Overall Company Footprint Analysis
  3.4.1 2.5D and 3D IC Packaging Market: Region Footprint
  3.4.2 2.5D and 3D IC Packaging Market: Company Product Type Footprint
  3.4.3 2.5D and 3D IC Packaging Market: Company Product Application Footprint
3.5 Competitive Environment
  3.5.1 Historical Structure of the Industry
  3.5.2 Barriers of Market Entry
  3.5.3 Factors of Competition
3.6 Mergers, Acquisitions Activity

4 UNITED STATES VS CHINA VS REST OF THE WORLD (BY HEADQUARTER LOCATION)

4.1 United States VS China: 2.5D and 3D IC Packaging Revenue Comparison (by Headquarter Location)
  4.1.1 United States VS China: 2.5D and 3D IC Packaging Market Size Comparison (2018 & 2022 & 2029) (by Headquarter Location)
  4.1.2 United States VS China: 2.5D and 3D IC Packaging Revenue Market Share Comparison (2018 & 2022 & 2029)
4.2 United States Based Companies VS China Based Companies: 2.5D and 3D IC Packaging Consumption Value Comparison
  4.2.1 United States VS China: 2.5D and 3D IC Packaging Consumption Value Comparison (2018 & 2022 & 2029)
  4.2.2 United States VS China: 2.5D and 3D IC Packaging Consumption Value Market Share Comparison (2018 & 2022 & 2029)
4.3 United States Based 2.5D and 3D IC Packaging Companies and Market Share, 2018-2023
  4.3.1 United States Based 2.5D and 3D IC Packaging Companies, Headquarters (States, Country)
  4.3.2 United States Based Companies 2.5D and 3D IC Packaging Revenue, (2018-2023)

4.4 China Based Companies 2.5D and 3D IC Packaging Revenue and Market Share, 2018-2023
4.4.1 China Based 2.5D and 3D IC Packaging Companies, Company Headquarters (Province, Country)
4.4.2 China Based Companies 2.5D and 3D IC Packaging Revenue, (2018-2023)
4.5 Rest of World Based 2.5D and 3D IC Packaging Companies and Market Share, 2018-2023
4.5.1 Rest of World Based 2.5D and 3D IC Packaging Companies, Headquarters (States, Country)
4.5.2 Rest of World Based Companies 2.5D and 3D IC Packaging Revenue, (2018-2023)

5 MARKET ANALYSIS BY TYPE

5.1 World 2.5D and 3D IC Packaging Market Size Overview by Type: 2018 VS 2022 VS 2029
5.2 Segment Introduction by Type
5.2.1 2.5D
5.2.2 3D TSV
5.2.3 3D Wafer-level Chip-scale Packaging
5.3 Market Segment by Type
5.3.1 World 2.5D and 3D IC Packaging Market Size by Type (2018-2023)
5.3.2 World 2.5D and 3D IC Packaging Market Size by Type (2024-2029)
5.3.3 World 2.5D and 3D IC Packaging Market Size Market Share by Type (2018-2029)

6 MARKET ANALYSIS BY APPLICATION

6.1 World 2.5D and 3D IC Packaging Market Size Overview by Application: 2018 VS 2022 VS 2029
6.2 Segment Introduction by Application
6.2.1 Consumer Electronics
6.2.2 Medical Devices
6.2.3 Communications and Telecom
6.2.4 Automotive
6.2.5 Automotive
6.3 Market Segment by Application
6.3.1 World 2.5D and 3D IC Packaging Market Size by Application (2018-2023)
6.3.2 World 2.5D and 3D IC Packaging Market Size by Application (2024-2029)

6.3.3 World 2.5D and 3D IC Packaging Market Size by Application (2018-2029)

7 COMPANY PROFILES

7.1 ASE Technology
7.1.1 ASE Technology Details
7.1.2 ASE Technology Major Business
7.1.3 ASE Technology 2.5D and 3D IC Packaging Product and Services
7.1.4 ASE Technology 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.1.5 ASE Technology Recent Developments/Updates
7.1.6 ASE Technology Competitive Strengths & Weaknesses
7.2 Samsung Electronics
7.2.1 Samsung Electronics Details
7.2.2 Samsung Electronics Major Business
7.2.3 Samsung Electronics 2.5D and 3D IC Packaging Product and Services
7.2.4 Samsung Electronics 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.2.5 Samsung Electronics Recent Developments/Updates
7.2.6 Samsung Electronics Competitive Strengths & Weaknesses
7.3 Toshiba
7.3.1 Toshiba Details
7.3.2 Toshiba Major Business
7.3.3 Toshiba 2.5D and 3D IC Packaging Product and Services
7.3.4 Toshiba 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.3.5 Toshiba Recent Developments/Updates
7.3.6 Toshiba Competitive Strengths & Weaknesses
7.4 STMicroelectronics
7.4.1 STMicroelectronics Details
7.4.2 STMicroelectronics Major Business
7.4.3 STMicroelectronics 2.5D and 3D IC Packaging Product and Services
7.4.4 STMicroelectronics 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.4.5 STMicroelectronics Recent Developments/Updates
7.4.6 STMicroelectronics Competitive Strengths & Weaknesses
7.5 Xilinx
7.5.1 Xilinx Details
7.5.2 Xilinx Major Business

7.5.3 Xilinx 2.5D and 3D IC Packaging Product and Services
7.5.4 Xilinx 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.5.5 Xilinx Recent Developments/Updates
7.5.6 Xilinx Competitive Strengths & Weaknesses
7.6 Intel
7.6.1 Intel Details
7.6.2 Intel Major Business
7.6.3 Intel 2.5D and 3D IC Packaging Product and Services
7.6.4 Intel 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.6.5 Intel Recent Developments/Updates
7.6.6 Intel Competitive Strengths & Weaknesses
7.7 Micron Technology
7.7.1 Micron Technology Details
7.7.2 Micron Technology Major Business
7.7.3 Micron Technology 2.5D and 3D IC Packaging Product and Services
7.7.4 Micron Technology 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.7.5 Micron Technology Recent Developments/Updates
7.7.6 Micron Technology Competitive Strengths & Weaknesses
7.8 TSMC
7.8.1 TSMC Details
7.8.2 TSMC Major Business
7.8.3 TSMC 2.5D and 3D IC Packaging Product and Services
7.8.4 TSMC 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.8.5 TSMC Recent Developments/Updates
7.8.6 TSMC Competitive Strengths & Weaknesses
7.9 SK Hynix
7.9.1 SK Hynix Details
7.9.2 SK Hynix Major Business
7.9.3 SK Hynix 2.5D and 3D IC Packaging Product and Services
7.9.4 SK Hynix 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.9.5 SK Hynix Recent Developments/Updates
7.9.6 SK Hynix Competitive Strengths & Weaknesses
7.10 Amkor Technology
7.10.1 Amkor Technology Details

+44 20 8123 2220
info@marketpublishers.com

7.10.2 Amkor Technology Major Business
7.10.3 Amkor Technology 2.5D and 3D IC Packaging Product and Services
7.10.4 Amkor Technology 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.10.5 Amkor Technology Recent Developments/Updates
7.10.6 Amkor Technology Competitive Strengths & Weaknesses
7.11 GlobalFoundries
7.11.1 GlobalFoundries Details
7.11.2 GlobalFoundries Major Business
7.11.3 GlobalFoundries 2.5D and 3D IC Packaging Product and Services
7.11.4 GlobalFoundries 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.11.5 GlobalFoundries Recent Developments/Updates
7.11.6 GlobalFoundries Competitive Strengths & Weaknesses
7.12 SanDisk (Western Digital)
7.12.1 SanDisk (Western Digital) Details
7.12.2 SanDisk (Western Digital) Major Business
7.12.3 SanDisk (Western Digital) 2.5D and 3D IC Packaging Product and Services
7.12.4 SanDisk (Western Digital) 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.12.5 SanDisk (Western Digital) Recent Developments/Updates
7.12.6 SanDisk (Western Digital) Competitive Strengths & Weaknesses
7.13 Synopsys
7.13.1 Synopsys Details
7.13.2 Synopsys Major Business
7.13.3 Synopsys 2.5D and 3D IC Packaging Product and Services
7.13.4 Synopsys 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.13.5 Synopsys Recent Developments/Updates
7.13.6 Synopsys Competitive Strengths & Weaknesses
7.14 Invensas
7.14.1 Invensas Details
7.14.2 Invensas Major Business
7.14.3 Invensas 2.5D and 3D IC Packaging Product and Services
7.14.4 Invensas 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.14.5 Invensas Recent Developments/Updates
7.14.6 Invensas Competitive Strengths & Weaknesses
7.15 Siliconware Precision Industries

+44 20 8123 2220
info@marketpublishers.com

7.15.1 Siliconware Precision Industries Details
7.15.2 Siliconware Precision Industries Major Business
7.15.3 Siliconware Precision Industries 2.5D and 3D IC Packaging Product and Services
7.15.4 Siliconware Precision Industries 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.15.5 Siliconware Precision Industries Recent Developments/Updates
7.15.6 Siliconware Precision Industries Competitive Strengths & Weaknesses
7.16 Jiangsu Changjiang Electronics
7.16.1 Jiangsu Changjiang Electronics Details
7.16.2 Jiangsu Changjiang Electronics Major Business
7.16.3 Jiangsu Changjiang Electronics 2.5D and 3D IC Packaging Product and Services
7.16.4 Jiangsu Changjiang Electronics 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.16.5 Jiangsu Changjiang Electronics Recent Developments/Updates
7.16.6 Jiangsu Changjiang Electronics Competitive Strengths & Weaknesses
7.17 Powertech Technology
7.17.1 Powertech Technology Details
7.17.2 Powertech Technology Major Business
7.17.3 Powertech Technology 2.5D and 3D IC Packaging Product and Services
7.17.4 Powertech Technology 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023)
7.17.5 Powertech Technology Recent Developments/Updates
7.17.6 Powertech Technology Competitive Strengths & Weaknesses

8 INDUSTRY CHAIN ANALYSIS

8.1 2.5D and 3D IC Packaging Industry Chain
8.2 2.5D and 3D IC Packaging Upstream Analysis
8.3 2.5D and 3D IC Packaging Midstream Analysis
8.4 2.5D and 3D IC Packaging Downstream Analysis

9 RESEARCH FINDINGS AND CONCLUSION

10 APPENDIX

10.1 Methodology
10.2 Research Process and Data Source

10.3 Disclaimer

+44 20 8123 2220
info@marketpublishers.com

List Of Tables

LIST OF TABLES

Table 1. World 2.5D and 3D IC Packaging Revenue by Region (2018, 2022 and 2029) & (USD Million), (by Headquarter Location)
Table 2. World 2.5D and 3D IC Packaging Revenue by Region (2018-2023) & (USD Million), (by Headquarter Location)
Table 3. World 2.5D and 3D IC Packaging Revenue by Region (2024-2029) & (USD Million), (by Headquarter Location)
Table 4. World 2.5D and 3D IC Packaging Revenue Market Share by Region (2018-2023), (by Headquarter Location)
Table 5. World 2.5D and 3D IC Packaging Revenue Market Share by Region (2024-2029), (by Headquarter Location)
Table 6. Major Market Trends
Table 7. World 2.5D and 3D IC Packaging Consumption Value Growth Rate Forecast by Region (2018 & 2022 & 2029) & (USD Million)
Table 8. World 2.5D and 3D IC Packaging Consumption Value by Region (2018-2023) & (USD Million)
Table 9. World 2.5D and 3D IC Packaging Consumption Value Forecast by Region (2024-2029) & (USD Million)
Table 10. World 2.5D and 3D IC Packaging Revenue by Player (2018-2023) & (USD Million)
Table 11. Revenue Market Share of Key 2.5D and 3D IC Packaging Players in 2022
Table 12. World 2.5D and 3D IC Packaging Industry Rank of Major Player, Based on Revenue in 2022
Table 13. Global 2.5D and 3D IC Packaging Company Evaluation Quadrant
Table 14. Head Office of Key 2.5D and 3D IC Packaging Player
Table 15. 2.5D and 3D IC Packaging Market: Company Product Type Footprint
Table 16. 2.5D and 3D IC Packaging Market: Company Product Application Footprint
Table 17. 2.5D and 3D IC Packaging Mergers & Acquisitions Activity
Table 18. United States VS China 2.5D and 3D IC Packaging Market Size Comparison, (2018 & 2022 & 2029) & (USD Million)
Table 19. United States VS China 2.5D and 3D IC Packaging Consumption Value Comparison, (2018 & 2022 & 2029) & (USD Million)
Table 20. United States Based 2.5D and 3D IC Packaging Companies, Headquarters (States, Country)
Table 21. United States Based Companies 2.5D and 3D IC Packaging Revenue, (2018-2023) & (USD Million)

Table 22. United States Based Companies 2.5D and 3D IC Packaging Revenue Market Share (2018-2023)
Table 23. China Based 2.5D and 3D IC Packaging Companies, Headquarters (Province, Country)
Table 24. China Based Companies 2.5D and 3D IC Packaging Revenue, (2018-2023) & (USD Million)
Table 25. China Based Companies 2.5D and 3D IC Packaging Revenue Market Share (2018-2023)
Table 26. Rest of World Based 2.5D and 3D IC Packaging Companies, Headquarters (States, Country)
Table 27. Rest of World Based Companies 2.5D and 3D IC Packaging Revenue, (2018-2023) & (USD Million)
Table 28. Rest of World Based Companies 2.5D and 3D IC Packaging Revenue Market Share (2018-2023)
Table 29. World 2.5D and 3D IC Packaging Market Size by Type, (USD Million), 2018 & 2022 & 2029
Table 30. World 2.5D and 3D IC Packaging Market Size by Type (2018-2023) & (USD Million)
Table 31. World 2.5D and 3D IC Packaging Market Size by Type (2024-2029) & (USD Million)
Table 32. World 2.5D and 3D IC Packaging Market Size by Application, (USD Million), 2018 & 2022 & 2029
Table 33. World 2.5D and 3D IC Packaging Market Size by Application (2018-2023) & (USD Million)
Table 34. World 2.5D and 3D IC Packaging Market Size by Application (2024-2029) & (USD Million)
Table 35. ASE Technology Basic Information, Area Served and Competitors
Table 36. ASE Technology Major Business
Table 37. ASE Technology 2.5D and 3D IC Packaging Product and Services
Table 38. ASE Technology 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 39. ASE Technology Recent Developments/Updates
Table 40. ASE Technology Competitive Strengths & Weaknesses
Table 41. Samsung Electronics Basic Information, Area Served and Competitors
Table 42. Samsung Electronics Major Business
Table 43. Samsung Electronics 2.5D and 3D IC Packaging Product and Services
Table 44. Samsung Electronics 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 45. Samsung Electronics Recent Developments/Updates

+44 20 8123 2220
info@marketpublishers.com

Table 46. Samsung Electronics Competitive Strengths & Weaknesses
Table 47. Toshiba Basic Information, Area Served and Competitors
Table 48. Toshiba Major Business
Table 49. Toshiba 2.5D and 3D IC Packaging Product and Services
Table 50. Toshiba 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 51. Toshiba Recent Developments/Updates
Table 52. Toshiba Competitive Strengths & Weaknesses
Table 53. STMicroelectronics Basic Information, Area Served and Competitors
Table 54. STMicroelectronics Major Business
Table 55. STMicroelectronics 2.5D and 3D IC Packaging Product and Services
Table 56. STMicroelectronics 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 57. STMicroelectronics Recent Developments/Updates
Table 58. STMicroelectronics Competitive Strengths & Weaknesses
Table 59. Xilinx Basic Information, Area Served and Competitors
Table 60. Xilinx Major Business
Table 61. Xilinx 2.5D and 3D IC Packaging Product and Services
Table 62. Xilinx 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 63. Xilinx Recent Developments/Updates
Table 64. Xilinx Competitive Strengths & Weaknesses
Table 65. Intel Basic Information, Area Served and Competitors
Table 66. Intel Major Business
Table 67. Intel 2.5D and 3D IC Packaging Product and Services
Table 68. Intel 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 69. Intel Recent Developments/Updates
Table 70. Intel Competitive Strengths & Weaknesses
Table 71. Micron Technology Basic Information, Area Served and Competitors
Table 72. Micron Technology Major Business
Table 73. Micron Technology 2.5D and 3D IC Packaging Product and Services
Table 74. Micron Technology 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 75. Micron Technology Recent Developments/Updates
Table 76. Micron Technology Competitive Strengths & Weaknesses
Table 77. TSMC Basic Information, Area Served and Competitors
Table 78. TSMC Major Business
Table 79. TSMC 2.5D and 3D IC Packaging Product and Services

Table 80. TSMC 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 81. TSMC Recent Developments/Updates
Table 82. TSMC Competitive Strengths & Weaknesses
Table 83. SK Hynix Basic Information, Area Served and Competitors
Table 84. SK Hynix Major Business
Table 85. SK Hynix 2.5D and 3D IC Packaging Product and Services
Table 86. SK Hynix 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 87. SK Hynix Recent Developments/Updates
Table 88. SK Hynix Competitive Strengths & Weaknesses
Table 89. Amkor Technology Basic Information, Area Served and Competitors
Table 90. Amkor Technology Major Business
Table 91. Amkor Technology 2.5D and 3D IC Packaging Product and Services
Table 92. Amkor Technology 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 93. Amkor Technology Recent Developments/Updates
Table 94. Amkor Technology Competitive Strengths & Weaknesses
Table 95. GlobalFoundries Basic Information, Area Served and Competitors
Table 96. GlobalFoundries Major Business
Table 97. GlobalFoundries 2.5D and 3D IC Packaging Product and Services
Table 98. GlobalFoundries 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 99. GlobalFoundries Recent Developments/Updates
Table 100. GlobalFoundries Competitive Strengths & Weaknesses
Table 101. SanDisk (Western Digital) Basic Information, Area Served and Competitors
Table 102. SanDisk (Western Digital) Major Business
Table 103. SanDisk (Western Digital) 2.5D and 3D IC Packaging Product and Services
Table 104. SanDisk (Western Digital) 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 105. SanDisk (Western Digital) Recent Developments/Updates
Table 106. SanDisk (Western Digital) Competitive Strengths & Weaknesses
Table 107. Synopsys Basic Information, Area Served and Competitors
Table 108. Synopsys Major Business
Table 109. Synopsys 2.5D and 3D IC Packaging Product and Services
Table 110. Synopsys 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 111. Synopsys Recent Developments/Updates
Table 112. Synopsys Competitive Strengths & Weaknesses

Table 113. Invensas Basic Information, Area Served and Competitors
Table 114. Invensas Major Business
Table 115. Invensas 2.5D and 3D IC Packaging Product and Services
Table 116. Invensas 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 117. Invensas Recent Developments/Updates
Table 118. Invensas Competitive Strengths & Weaknesses
Table 119. Siliconware Precision Industries Basic Information, Area Served and Competitors
Table 120. Siliconware Precision Industries Major Business
Table 121. Siliconware Precision Industries 2.5D and 3D IC Packaging Product and Services
Table 122. Siliconware Precision Industries 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 123. Siliconware Precision Industries Recent Developments/Updates
Table 124. Siliconware Precision Industries Competitive Strengths & Weaknesses
Table 125. Jiangsu Changjiang Electronics Basic Information, Area Served and Competitors
Table 126. Jiangsu Changjiang Electronics Major Business
Table 127. Jiangsu Changjiang Electronics 2.5D and 3D IC Packaging Product and Services
Table 128. Jiangsu Changjiang Electronics 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 129. Jiangsu Changjiang Electronics Recent Developments/Updates
Table 130. Powertech Technology Basic Information, Area Served and Competitors
Table 131. Powertech Technology Major Business
Table 132. Powertech Technology 2.5D and 3D IC Packaging Product and Services
Table 133. Powertech Technology 2.5D and 3D IC Packaging Revenue, Gross Margin and Market Share (2018-2023) & (USD Million)
Table 134. Global Key Players of 2.5D and 3D IC Packaging Upstream (Raw Materials)
Table 135. 2.5D and 3D IC Packaging Typical Customers

+44 20 8123 2220
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

Figure 1. 2.5D and 3D IC Packaging Picture
Figure 2. World 2.5D and 3D IC Packaging Total Market Size: 2018 & 2022 & 2029, (USD Million)
Figure 3. World 2.5D and 3D IC Packaging Total Market Size (2018-2029) & (USD Million)
Figure 4. World 2.5D and 3D IC Packaging Revenue Market Share by Region (2018, 2022 and 2029) & (USD Million) , (by Headquarter Location)
Figure 5. World 2.5D and 3D IC Packaging Revenue Market Share by Region (2018-2029), (by Headquarter Location)
Figure 6. United States Based Company 2.5D and 3D IC Packaging Revenue (2018-2029) & (USD Million)
Figure 7. China Based Company 2.5D and 3D IC Packaging Revenue (2018-2029) & (USD Million)
Figure 8. Europe Based Company 2.5D and 3D IC Packaging Revenue (2018-2029) & (USD Million)
Figure 9. Japan Based Company 2.5D and 3D IC Packaging Revenue (2018-2029) & (USD Million)
Figure 10. South Korea Based Company 2.5D and 3D IC Packaging Revenue (2018-2029) & (USD Million)
Figure 11. ASEAN Based Company 2.5D and 3D IC Packaging Revenue (2018-2029) & (USD Million)
Figure 12. India Based Company 2.5D and 3D IC Packaging Revenue (2018-2029) & (USD Million)
Figure 13. 2.5D and 3D IC Packaging Market Drivers
Figure 14. Factors Affecting Demand
Figure 15. World 2.5D and 3D IC Packaging Consumption Value (2018-2029) & (USD Million)
Figure 16. World 2.5D and 3D IC Packaging Consumption Value Market Share by Region (2018-2029)
Figure 17. United States 2.5D and 3D IC Packaging Consumption Value (2018-2029) & (USD Million)
Figure 18. China 2.5D and 3D IC Packaging Consumption Value (2018-2029) & (USD Million)
Figure 19. Europe 2.5D and 3D IC Packaging Consumption Value (2018-2029) & (USD Million)

Figure 20. Japan 2.5D and 3D IC Packaging Consumption Value (2018-2029) & (USD Million)
Figure 21. South Korea 2.5D and 3D IC Packaging Consumption Value (2018-2029) & (USD Million)
Figure 22. ASEAN 2.5D and 3D IC Packaging Consumption Value (2018-2029) & (USD Million)
Figure 23. India 2.5D and 3D IC Packaging Consumption Value (2018-2029) & (USD Million)
Figure 24. Producer Shipments of 2.5D and 3D IC Packaging by Player Revenue ($MM) and Market Share (%): 2022
Figure 25. Global Four-firm Concentration Ratios (CR4) for 2.5D and 3D IC Packaging Markets in 2022
Figure 26. Global Four-firm Concentration Ratios (CR8) for 2.5D and 3D IC Packaging Markets in 2022
Figure 27. United States VS China: 2.5D and 3D IC Packaging Revenue Market Share Comparison (2018 & 2022 & 2029)
Figure 28. United States VS China: 2.5D and 3D IC Packaging Consumption Value Market Share Comparison (2018 & 2022 & 2029)
Figure 29. World 2.5D and 3D IC Packaging Market Size by Type, (USD Million), 2018 & 2022 & 2029
Figure 30. World 2.5D and 3D IC Packaging Market Size Market Share by Type in 2022
Figure 31. 2.5D
Figure 32. 3D TSV
Figure 33. 3D Wafer-level Chip-scale Packaging
Figure 34. World 2.5D and 3D IC Packaging Market Size Market Share by Type (2018-2029)
Figure 35. World 2.5D and 3D IC Packaging Market Size by Application, (USD Million), 2018 & 2022 & 2029
Figure 36. World 2.5D and 3D IC Packaging Market Size Market Share by Application in 2022
Figure 37. Consumer Electronics
Figure 38. Medical Devices
Figure 39. Communications and Telecom
Figure 40. Automotive
Figure 41. Other
Figure 42. 2.5D and 3D IC Packaging Industrial Chain
Figure 43. Methodology
Figure 44. Research Process and Data Source

I would like to order

Product name: Global 2.5D and 3D IC Packaging Supply, Demand and Key Producers, 2023-2029

Product link: https://marketpublishers.com/r/GF887B996E90EN.html

Price: US$ 4,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/GF887B996E90EN.html

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:

Last name:

Email:

Company:

Address:

City:

Zip code:

Country:

Tel:

Fax:

Your message:

**All fields are required

Custumer signature ____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at https://marketpublishers.com/docs/terms.html

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970